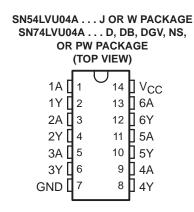
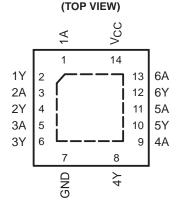
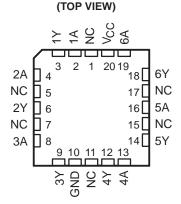
- 2-V to 5.5-V V_{CC} Operation
- Unbuffered Outputs
- Max t_{pd} of 6.5 ns at 5 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2.3 V at V_{CC} = 3.3 V, T_A = 25°C
- Support Mixed-Mode Voltage Operation on All Ports
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)





SN74LVU04A . . . RGY PACKAGE



SN54LVU04A . . . FK PACKAGE

NC - No internal connection

description/ordering information

These hex inverters are designed for 2-V to 5.5-V V_{CC} operation.

The 'LVU04A devices contain six independent inverters with unbuffered outputs. These devices perform the Boolean function $Y = \overline{A}$.

ORDERING INFORMATION

TA	PACK	AGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	QFN – RGY	Reel of 1000	SN74LVU04ARGYR	LVU04A
-40°C to 85°C	COIC D	Tube of 50	SN74LVU04AD	11/1/1044
	SOIC - D	Reel of 2500	SN74LVU04ADR	LVU04A
	SOP - NS	Reel of 2000	SN74LVU04ANSR	LVU04A
	SSOP – DB	Reel of 2000	SN74LVU04ADBR	LU04A
		Tube of 90	SN74LVU04APW	
	TSSOP - PW	Reel of 2000	SN74LVU04APWR	LU04A
		Reel of 250	SN74LVU04APWT	
	TVSOP - DGV	Reel of 2000	SN74LVU04ADGVR	LU04A
	CDIP – J	Tube of 25	SNJ54LVU04AJ	SNJ54LVU04AJ
-55°C to 125°C	CFP – W	Tube of 150	SNJ54LVU04AW	SNJ54LVU04AW
	LCCC - FK	Tube of 85	SNJ54LVU04AFK	SNJ54LVU04AFK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



FUNCTION TABLE (each inverter)

INPUT A	OUTPUT Y
Н	L
L	Н

logic diagram, each inverter (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V_{CC}	–0.5 V to 7 V
Output voltage range, V _O (see Notes 1 and 2)	
Input clamp current, $I_{ K }(V_{ I } < 0)$	–20 mA
Output clamp current, I _{OK} (V _O < 0)	
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ _{JA} (see Note 3): D package	86°C/W
(see Note 3): DB package	96°C/W
(see Note 3): DGV package	127°C/W
(see Note 3): NS package	76°C/W
(see Note 3): PW package	113°C/W
(see Note 4): RGY package	47°C/W
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. This value is limited to 5.5 V maximum.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.
 - 4. The package thermal impedance is calculated in accordance with JESD 51-5.



recommended operating conditions (see Note 5)

			SN54L	VU04A	SN74L	VU04A		
			MIN	MAX	MIN	MAX	UNIT	
VCC	Supply voltage		2	5.5	2	5.5	V	
		V _{CC} = 2 V	1.7		1.7			
.,	LPak Java Canada sakana	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	V _{CC} × 0.8		$V_{CC} \times 0.8$		V	
VIH	High-level input voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	$V_{CC} \times 0.8$		$V_{CC} \times 0.8$		V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	$V_{CC} \times 0.8$		$V_{CC} \times 0.8$			
		V _{CC} = 2 V		0.3		0.3		
.,	Laveland insert valtage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		$V_{CC} \times 0.2$		$V_{CC} \times 0.2$.,	
V_{IL}	Low-level input voltage	V _{CC} = 3 V to 3.6 V		$V_{CC} \times 0.2$		$V_{CC} \times 0.2$	V	
		V _{CC} = 4.5 V to 5.5 V		$V_{CC} \times 0.2$		$V_{CC} \times 0.2$		
VI	Input voltage		0	5.5	0	5.5	V	
VO	Output voltage		0	VCC	0	Vcc	V	
		V _{CC} = 2 V	1	-50		-50	μΑ	
	LPak lavel sylvet symmet	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	20	-2		-2		
ЮН	High-level output current	V _{CC} = 3 V to 3.6 V	20	-6		-6	mA	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	P	-12		-12		
		V _{CC} = 2 V		50		50	μΑ	
	Landard advisarious	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2		2		
lOL	Low-level output current	V _{CC} = 3 V to 3.6 V		6		6	mA	
		V _{CC} = 4.5 V to 5.5 V		12		12		
TA	Operating free-air temperature		-55	125	-40	85	°C	

NOTE 5: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS	.,	SN54	ILVU04A		SN74	LVU04A	١	
PARAMETER	TEST CONDITIONS	v _{CC}	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
	I _{OH} = -50 μA	2 V to 5.5 V	V _{CC} -0.1			V _{CC} -0.1			
V	$I_{OH} = -2 \text{ mA}$	2.3 V	2			2			V
VOH	I _{OH} = -6 mA	3 V	2.48	, sh		2.48			V
	$I_{OH} = -12 \text{ mA}$	4.5 V	3.8	,S		3.8			
	I _{OL} = 50 μA	2 V to 5.5 V		77	0.1			0.1	
V = :	$I_{OL} = 2 \text{ mA}$	2.3 V			0.4			0.4	.,
VOL	I _{OL} = 6 mA	3 V	"//		0.44			0.44	V
	I _{OL} = 12 mA	4.5 V	02		0.55			0.55	
lį	V _I = 5.5 V or GND	0 V to 5.5 V	Q		±1			±1	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			20			20	μΑ
C _i	$V_I = V_{CC}$ or GND	3.3 V		4			4		pF

SCES130L - MARCH 1998 - REVISED DECEMBER 2004

switching characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

242445	FROM TO		LOAD	T _A = 25°C			SN54LVU04A	SN74L	SN74LVU04A	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN MAX	MIN	MAX	UNIT
tool	۸	V	C _L = 15 pF		3.2*	10.9*	1* 14*	1	14	20
^t pd	A	ſ	C _L = 50 pF		6.6	13.4	1 16	1	16	ns

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

242445	FROM	то	LOAD T _A = 25°C SN54LVU04A SN74LVU			VU04A					
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN MA	MIN	MAX	UNIT	l
t	۸	V	C _L = 15 pF		2.5*	8.9*	1* 10.5	1	10.5		1
^t pd	A	r	C _L = 50 pF		4.7	11.4	(1 1:	3 1	13	ns	

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETER	FROM	то	LOAD	T _A = 25°C			SN54LVU04A	SN74L	SN74LVU04A	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN MA	MIN	MAX	UNIT
to a	^	V	C _L = 15 pF		2.2*	5.5*	1* 6.5	* 1	6.5	
^t pd	A	r	C _L = 50 pF		3.9	7	Q1	3 1	8	ns

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics, $V_{CC} = 3.3 \text{ V}$, $C_L = 50 \text{ pF}$, $T_A = 25^{\circ}\text{C}$ (see Note 6)

	DADAMETED	SN7			
	PARAMETER	MIN	TYP	MAX	UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.5	0.8	V
V _{OL} (V)	Quiet output, minimum dynamic V _{OL}		-0.1	-0.8	V
VOH(V)	Quiet output, minimum dynamic VOH		3		V
V _{IH(D)}	High-level dynamic input voltage	2.31			V
V _{IL(D)}	Low-level dynamic input voltage			0.99	V

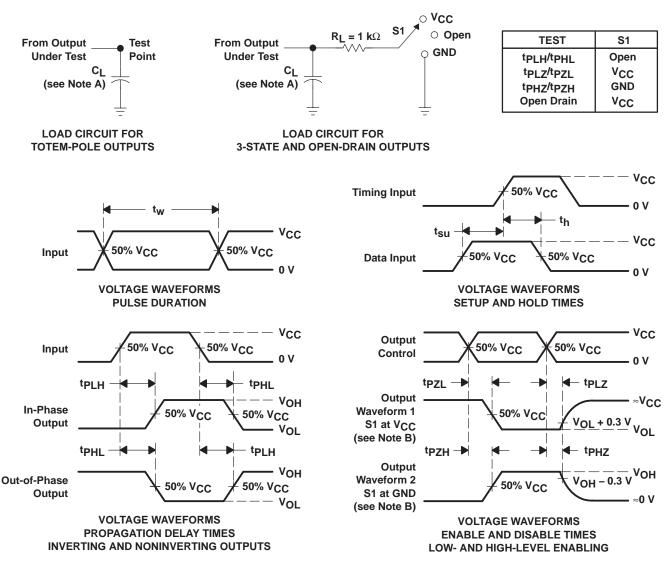
NOTE 6: Characteristics are for surface-mount packages only.

operating characteristics, T_A = 25°C

	PARAMETER	TEST CO	NDITIONS	VCC	TYP	UNIT
C., .1	Dower dissination conscitance	C 50 pE	f = 10 MHz	3.3 V	5.6	, E
Cpd	Power dissipation capacitance	$C_L = 50 \text{ pF},$	I = 10 WIHZ	5 V	6.7	pF



PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , $t_f \leq$ 3 ns. $t_f \leq$ 3 ns.
 - D. The outputs are measured one at a time, with one input transition per measurement.
 - E. tpLZ and tpHZ are the same as tdis.
 - F. tpzi and tpzH are the same as ten.
 - G. tpHL and tpLH are the same as tpd.
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms







10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
SN74LVU04AD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVU04A	Samples
SN74LVU04ADBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LU04A	Samples
SN74LVU04ADG4	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVU04A	Samples
SN74LVU04ADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVU04A	Samples
SN74LVU04ANSR	ACTIVE	so	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVU04A	Samples
SN74LVU04APW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LU04A	Samples
SN74LVU04APWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LU04A	Samples
SN74LVU04APWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LU04A	Samples
SN74LVU04APWT	ACTIVE	TSSOP	PW	14	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LU04A	Samples
SN74LVU04APWTE4	ACTIVE	TSSOP	PW	14	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LU04A	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: Til defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



PACKAGE OPTION ADDENDUM

10-Dec-2020

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN74LVU04A:

Automotive: SN74LVU04A-Q1

NOTE: Qualified Version Definitions:

Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

PACKAGE MATERIALS INFORMATION

www.ti.com 30-Dec-2020

TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVU04ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LVU04ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LVU04APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LVU04APWT	TSSOP	PW	14	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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*All dimensions are nominal

7 III GITTIOTOTOTO GITO TIOTITIGI							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVU04ADR	SOIC	D	14	2500	853.0	449.0	35.0
SN74LVU04ANSR	SO	NS	14	2000	853.0	449.0	35.0
SN74LVU04APWR	TSSOP	PW	14	2000	853.0	449.0	35.0
SN74LVU04APWT	TSSOP	PW	14	250	853.0	449.0	35.0

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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